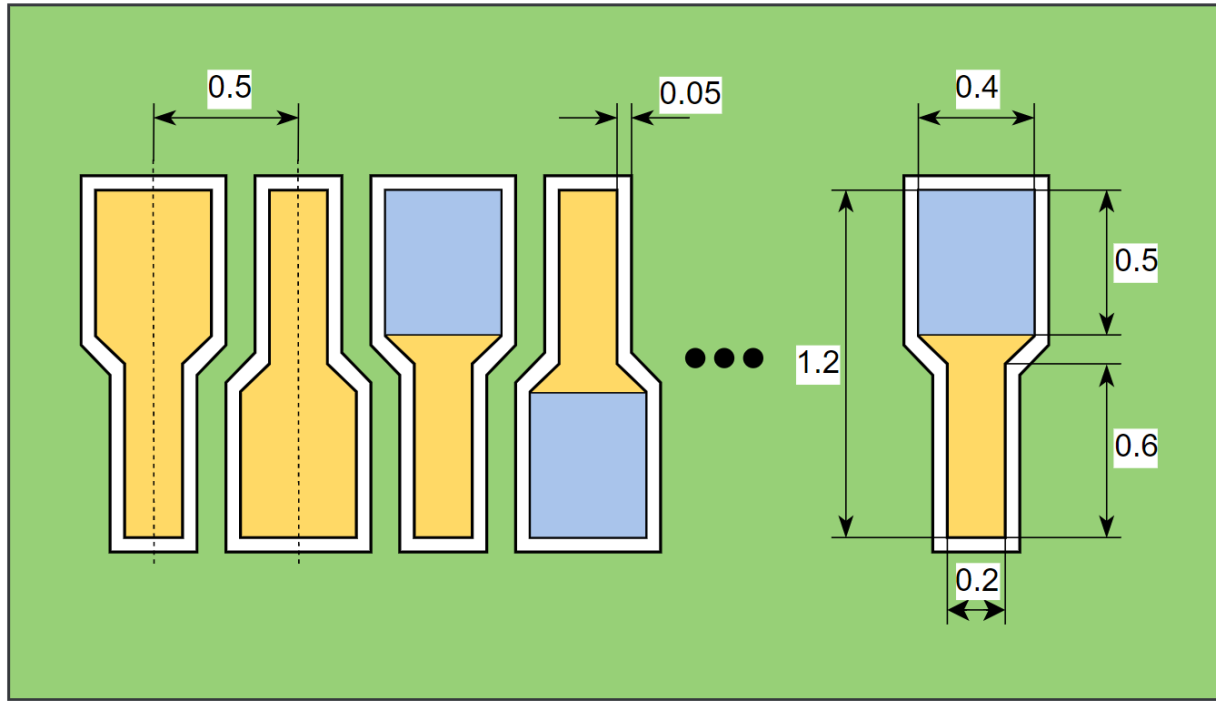






Modified LQFP land pattern for solder bridging prevention

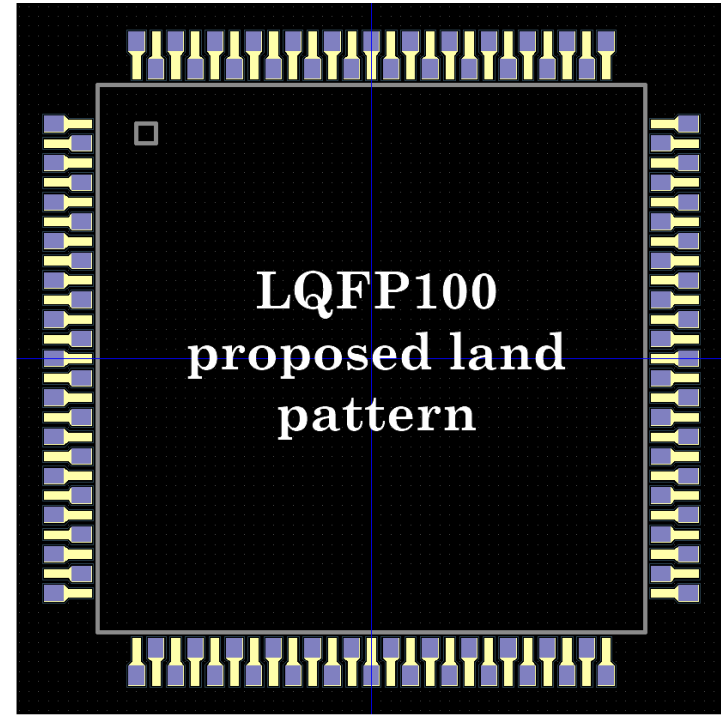
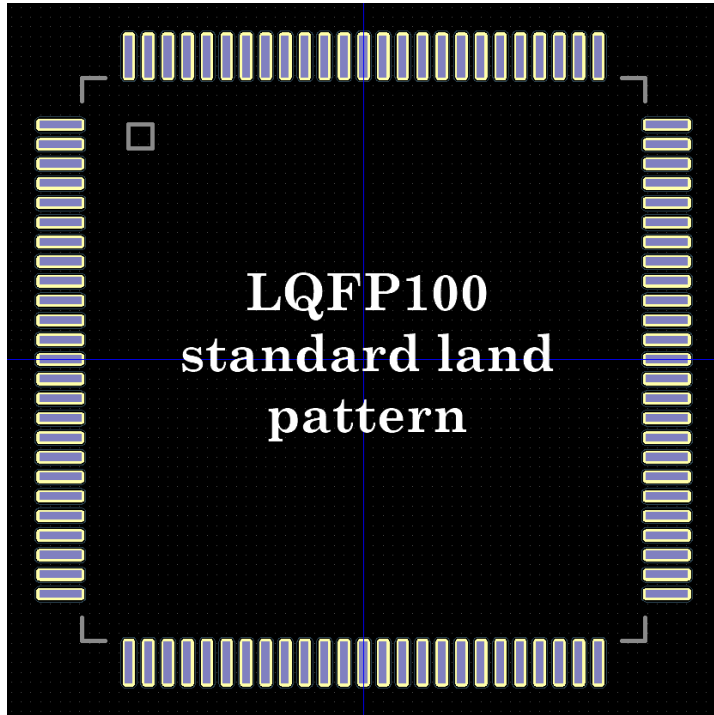
(0.5mm pitch)

Proposed land pattern (mm)



-  solder mask
-  solder mask opening
-  copper
-  solder paste

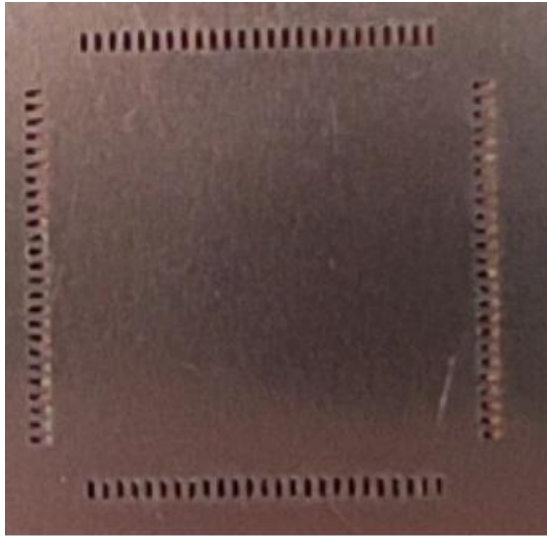
Preview in pattern editor



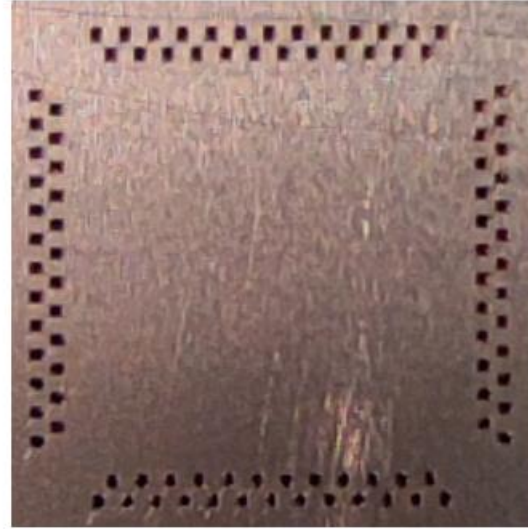
Features

- Solder bridging prevented
- Loose tolerances for stencil placement
- Better solder paste transfer (rectangular pads)
- Not suitable for hand soldering

Solder paste stencil

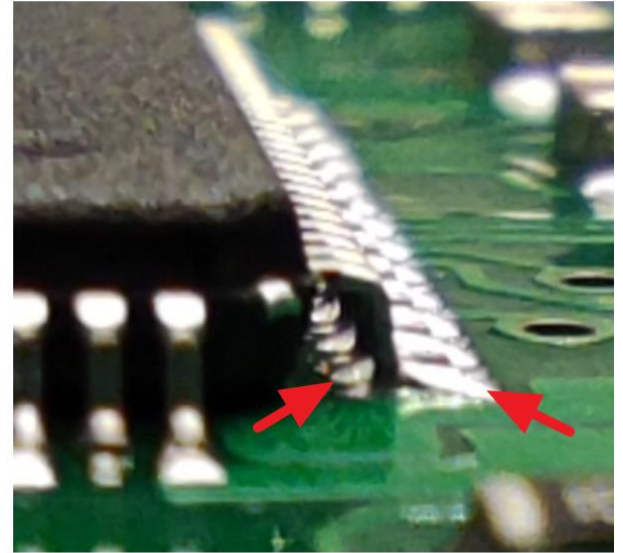
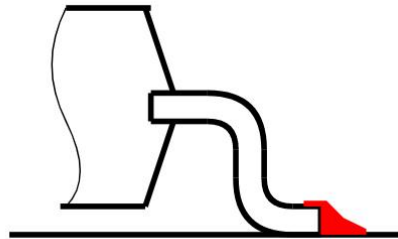
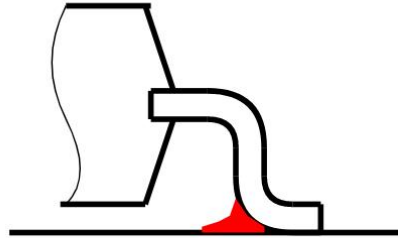
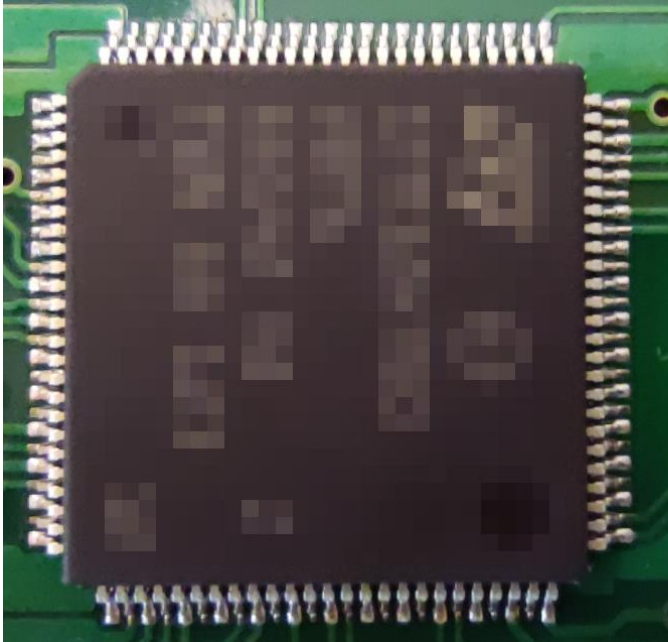


standard



proposed

Odd/even solder joints



Test environment and results

- Stencil thickness 0.12mm
- Solder paste MECHANIC XGZ40 Sn63Pb37
- Boards assembled 6 pcs, solder bridges: none
- For more details www.thundertronics.com,
e-mail: georgy.moshkin@outlook.com